

01-16-2001

Docket No. JCLA6704



12220

Form		5/9391	U.S. Department of Commerce
1-31-	PATENTS O	NLY	Patent and Trademark Office
	To the Honorable Assistant Cor original	nmissioner for Pate documents or copy	
1.	Name of conveying party(ies):	į.	Name/address of receiving
	Horng-Huei Tseng	Ì	Party(ies):
	Horng-Huer 13eng	,	nguard International Semiconductor orp.
3.	Nature of conveyance:	signment	np.
	☐ Merger ☐ Security Agreement ☐		123, Park Ave-3rd, Science-Based
	☐ Change of Name ☐ Reassignm	ent	Industrial Park, Hsinchu, Taiwan, R.O.C.
4.	Date(s) of execution: September 2	27, 2000.	A.O.C.
)	names of receiving parties
			ned? Yes X No
5.	Application number(s) or patent n	umber(s):	
	If this documents is being execution date of the applica	_	er with a new application, the ember 27, 2000.
	A. Patent Application No. (s)		B. Patent No. (s)
	A 3 3141 1 1		TV EN
	Additional numbers		☐ Yes ☑ No
6.	Name and address of party to who correspondence concerning documents		Total No. of applications and patents involved:
	should be mailed:		ONE(1)
		8.	Total fee (37 CFR §3.41): \$40.00
	J.C. Patents, Inc. 1340 Reynolds Ave., Suite 1	14	⊠ Enclosed
	Irvine, CA 92614		☐ Charge to Acct. No.
	(949) 660-0761		Total number of pages, including
			cover sheet, attachments and document 3.
	DO NO	T USE THIS SE	ACE
10.	Statement and Signature:		
	To the best of my knowledge		
	and correct and any attached co	py is a true co	py of the original document.
	:: 11	10 H	an 17 67 h
	iawei Huang ame of Person Signing	Signature	$\frac{\sqrt{2/27/2000}}{\text{Date}}$
110	and of t cison pigning	Signature	Date

Registration No. 43, 330

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PATENT REEL: 011413 FRAME: 0756

ASSIGNMENT

WHEREAS.

1. Horng-Huei Tseng

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: METHOD FOR FABRICATING A SOI (SILICON ON INSULATOR) DEVICE

[] Filed: Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, Vanguard International Semiconductor Corp. of 123, Park Ave-3rd, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

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ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

HOZNG-HULL TSEMG Signature:

Sole or First Joint Inventor: Horng-Huei Tseng

RECORDED: 12/27/2000

3ep. 27, 2000

Date:

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